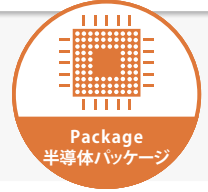


## Low-temperature curing Secondary mounting Underfill materials 低温硬化性二次実装アンダーフィル材



### Applications 用途

Mount reinforcement of semiconductor packages and electronic parts for Automotive camera modules, Millimeter-wave radar modules, ECU, etc.  
車載カメラモジュール、車載ミリ波レーダー用モジュール、車載 ECU などへの半導体パッケージや電子部品の実装補強



Cures at low temperatures and can be applied for mount-reinforcement of precision parts that need to be protected from high temperatures. Improves the mounting reliability of automotive parts, for which high bonding strength is required.  
低温で硬化し高温を嫌う精密部品の実装に対応、接合強度が求められる車載部品の実装信頼性に貢献

Cures at a low temp of 80°C  
After curing, Tg is 140°C or greater  
80°Cで低温硬化、硬化物 Tg は 140°C 以上

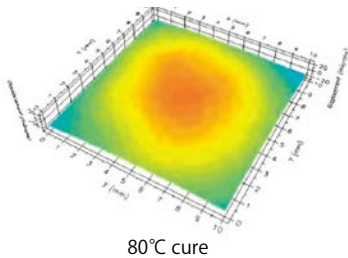
Smaller difference in heat shrinkage  
with other part, by high Tg  
高い Tg により低い熱収縮を実現

Possible to capillary flow up to 40mm  
in the gap of 20 μm  
20 μm の狭ギャップに最大 40mm 浸入可

### Moire data at Room temperature 室温反り測定データ (シャドウモアレ)

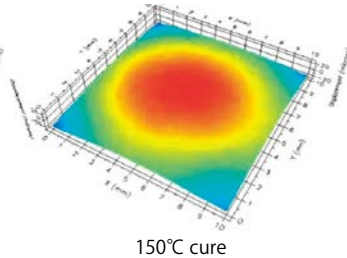
New Product

23 μm



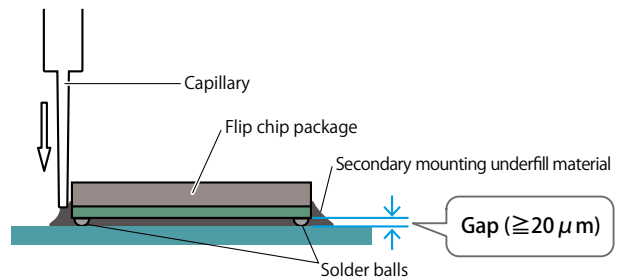
Conventional

66 μm

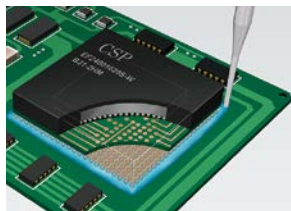


### Suitable for mounting in areas with small gaps 狭ギャップに対応

Cross Section of a Circuited Board Being Mounted



### Correspond to temperature cycle test under Automotive environment 車載環境下の温度サイクル試験にも対応



Item	New Product CV5350AS	Conventional
Temperature cycling test (TCT) -55°C ⇄ 125°C	1000 cycles Pass	300 cycles Pass

We also have "Corner reinforce type" suitable for partial reinforcement  
部分補強に適した「コーナー補強タイプ」も所有

### General properties 一般特性

Item	Unit	CV5350AS
Minimum flow gap	μm	20
Viscosity (25°C)	mPa·s	4000
Glass transition temperature (Tg)	°C	150
C.T.E.1	ppm/°C	30
Elastic modulus (25°C)	GPa	10
Potential for reworking	—	Not possible

The above data are typical values and not guaranteed values. 上記データは当社測定による代表値であり、保証値ではありません。